

1N5817 THRU 1N5819

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1.0A Axial Leaded Schottky Barrier Rectifiers 20V-40V

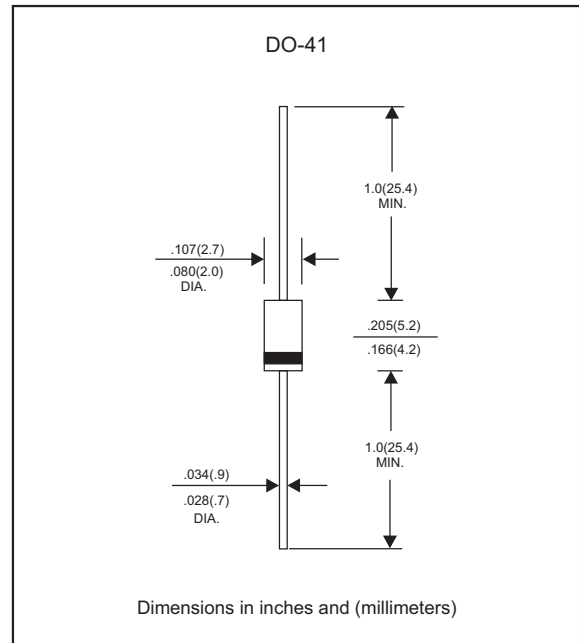
Features

- Axial lead type devices for through hole design
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High surge capability
- Guardring for overvoltage protection
- Ultra high-speed switching
- Silicon epitaxial planar chip, metal silicon junction
- Lead-free parts meet RoHS requirements

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-41
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight : Approximated 0.33 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	1N5817	1N5818	1N5819	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	Volts
Maximum RMS voltage	V_{RMS}	14	21	28	Volts
Maximum continuous reverse voltage	V_R	20	30	40	Volts
Maximum average forward rectified current	I_O	1.0			Amps
Non-repetitive peak forward surge current 8.3ms single half sine-wave	I_{FSM}	25			Amps
Typical junction capacitance (Note 1)	C_J	110			pF
Operating junction temperature range	T_J	-55 to +125			$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-65 to +175			$^{\circ}\text{C}$

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	1N5817	1N5818	1N5819	UNITS
Maximum instantaneous forward voltage at $I_F=1.0\text{A}$	V_F	0.45	0.55	0.60	Volts
Maximum reverse leakage current at rated V_R	I_R	0.5 10			mA mA

Thermal characteristics

PARAMETER	SYMBOLS	1N5817	1N5818	1N5819	UNITS
Typical thermal resistance junction to ambient	$R_{\theta JA}$	80			$^{\circ}\text{C} / \text{W}$

Note 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC

Rating and characteristic curves (1N5817 THRU 1N5819)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

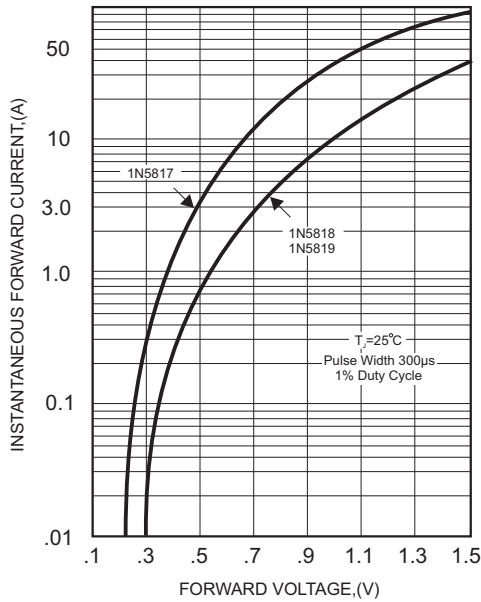


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

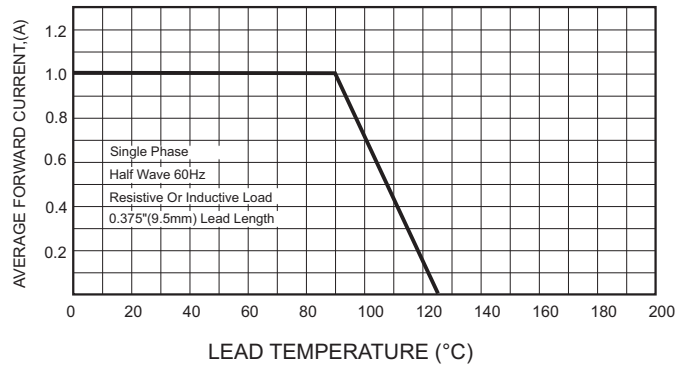


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

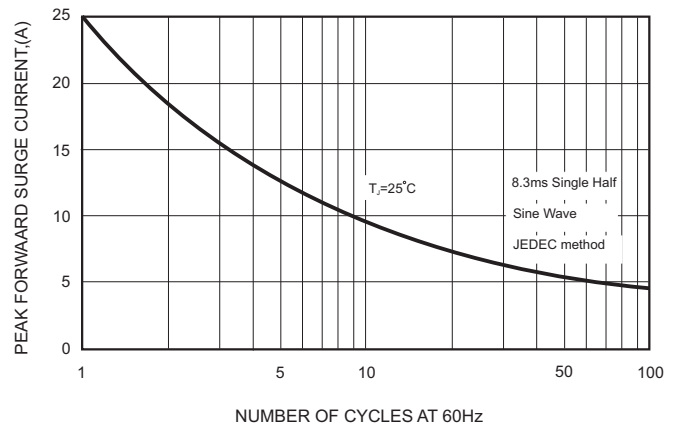


FIG.3- TYPICAL REVERSE CHARACTERISTICS

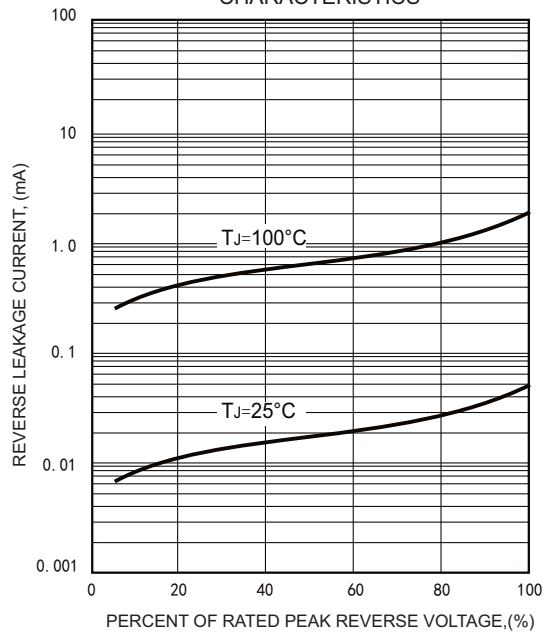
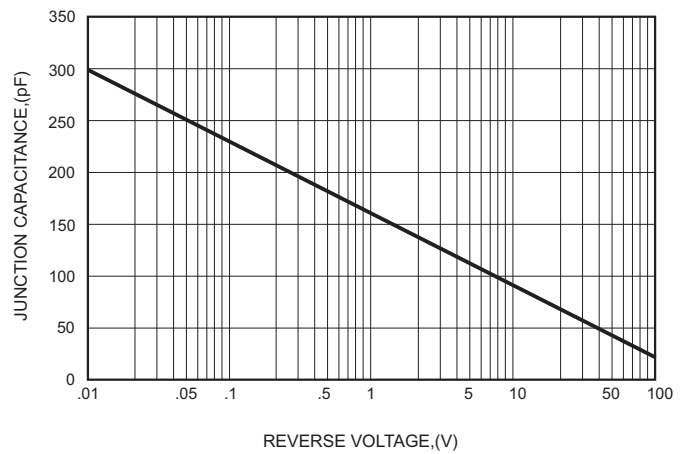


FIG.5-TYPICAL JUNCTION CAPACITANCE



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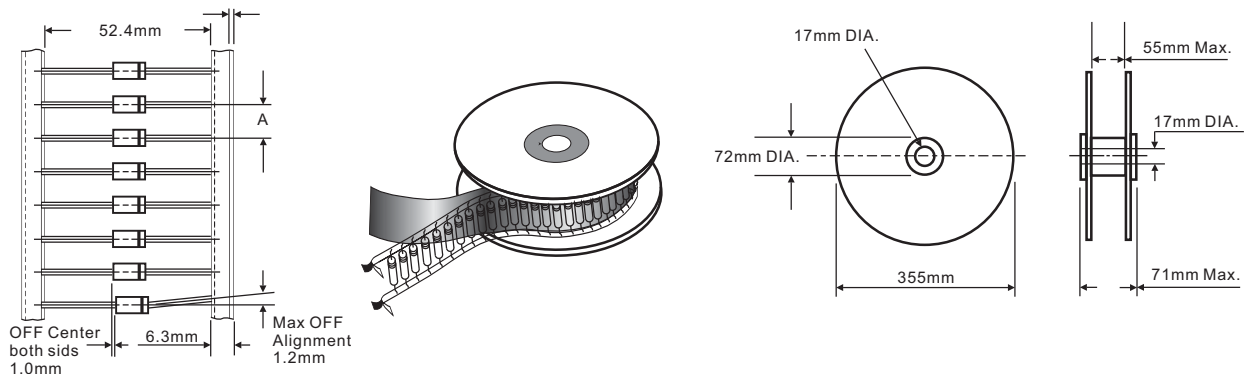
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode	1  2	1  2

Marking

Type number	Marking code
1N5817	1N5817
1N5818	1N5818
1N5819	1N5819

Taping & bulk specifications for AXIAL devices



REEL PACKING

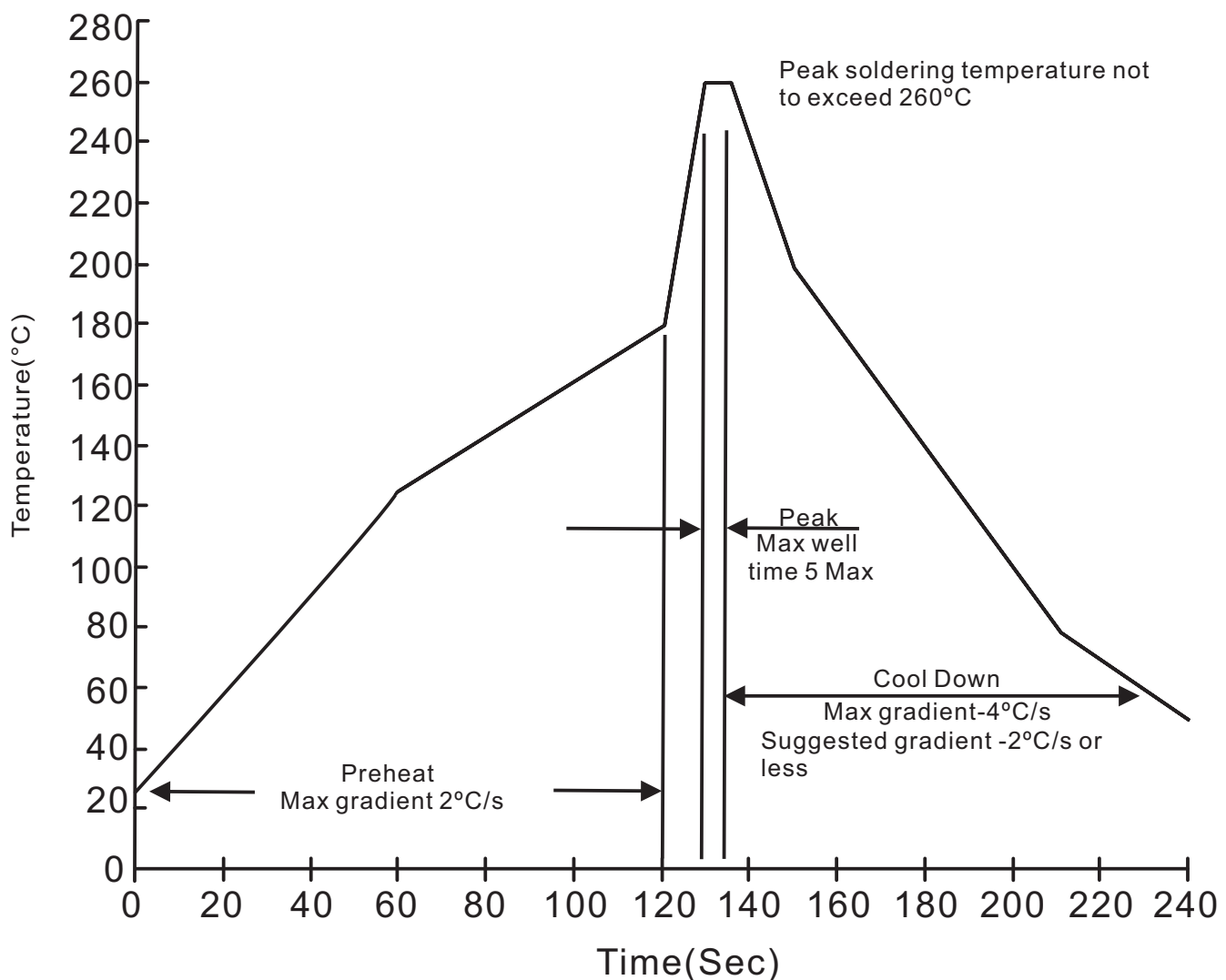
DEVICE CASE TYPE	Q'TY 1 (PCS / REEL)	COMPONENT SPACING "A" in FIG. A	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-41	5,000	5 mm	360 * 340 * 370	20,000	10.8

AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-41	5,000	260 * 83 * 160	440 * 270 * 340	50,000	20.0

1N5817 THRU 1N5819**BULK PACKING**

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-41	1,000	194 * 84 * 20	465 * 220 * 260	50,000	20.6

Suggested thermal profiles for soldering processes**1. Lead free temperature profile wave-soldering**

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm 5^{\circ}\text{C}$ for $10\pm 2\text{sec.}$ immerse body into solder $1/16''\pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. Pull Test	1.0kg in axial lead direction for 10 sec. $I_F = I_O$	MIL-STD-202F METHOD-211A
4. Bend Lead	1.0kg weight applied to each lead bending arc $90^{\circ}\pm 5^{\circ}$ for 3 times	MIL-STD-202F METHOD-211A
5. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
6. Forward Operation Life	Rated average rectifier current at $T_A = 25^{\circ}\text{C}$ for 500hrs. $T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min, on and off for 500 cycles.	MIL-STD-750D METHOD-1027
7. Intermittent Operation Life		MIL-STD-750D METHOD-1036
8. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
9. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
10. Forward Surge	8.3ms single half sine-wave one surge.	MIL-STD-750D METHOD-4066-2
11. Humidity	at $T_A = 85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
12. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031